



For Immediate Release:

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Austin Semiconductor, Inc. launches new iPEM Product family with its initial Product Release of a 1.2Gb, SDRAM-DDR in 219-PBGA

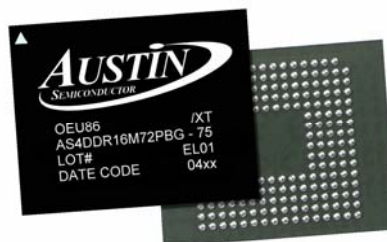
Austin, Texas - Austin Semiconductor, Inc. (ASI), a leading supplier of high-reliability (HI-REL) and ruggedized plastic encapsulated semiconductor products and services, announces the introduction of a new high integration product family. This family, based on integrated multiple silicon devices, is manufactured on an organic laminate micro-substrate and then encapsulated using industry standard plastic materials (iPEM). This product packaging technology allows for highly integrated products on a medium which exhibits improved space utilization, capacitance, and inductance, as well as, excellent thermal properties and controlled impedance over the monolithic building block approach. This packaging method provides the customer a means to meet the cost challenges of the Perry Initiative, while providing the high-reliability marketplace a product with additional advantages, such as the improvements mentioned above, as well as reducing the etch routing density, improving the PWB complexity and therefore the PWB cost.

The first Austin Semiconductor product utilizing this packaging technology is a multi-chip (die) SDRAM-DDR with a total density of 1.2Gb and organized as 16M x 72/80, fitting a footprint of 32mm x 25mm and containing a total of 219 balls which constitutes the electro-mechanical interface. This device will be immediately followed by the availability of the single data rate version (SDR) and the 2.4Gb DDR device will follow in late "Q3-2006" within the same footprint. This initial product, a multi-source device, is the first of many products to be released utilizing this packaging technology and has been used as the springboard for all the product definitions to follow.

Future iPEM introductions will include additional memory only as well as sub-system definitions. Each definition based on the multi-chip on micro-laminate encapsulated in plastic packaging model or iPEM.

Austin Semi is currently sampling DDR266 devices at full military temperature range and DDR333 devices are available for the industrial temperature range. Production orders are being accepted now. Lead-time and unit pricing is available via all Austin Semiconductor sales channels. A complete datasheet can be downloaded at www.austinsemiconductor.com.

Austin Semiconductor continues to show their support to HI-REL markets by continuously developing products defined for use in these environments, such as the AS4DDR16M72PBG. The iPEM product family will greatly increase the number plastic encapsulated products offered and enhance Austin's already comprehensive product and services offering.



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iPEM Product Family Summary:

- ✓ Integrated products based on multiple silicon devices, manufactured on an organic micro-laminate then over molded with standard industry plastic materials
- ✓ Integral power planes
- ✓ PBGA definitions with 1.27mm and 1.00mm ball pitches
- ✓ Improved Capacitance and Inductance levels
- ✓ Excellent thermal properties
- ✓ Space Saving footprint
- ✓ Improved parent PWB route densities therefore decreased parent PWB costs

AS4DDR1M72PBG features include:

- Total density:1.2Gb organized as 16M x 72/80
- DDR SDRAM, data rate = 200, 250, 266 and 333 Mbps (million bits per second)
- Core frequencies = 100, 125, 133 and 166 MHz
- 2.5V +/- 0.2V power supply
- 2.5V I/O supply (SSTL_2 compatible)
- Differential input clocks (CLK and CLK\)
- Internal pipelined, DDR architecture; two data accesses per clock cycle
- Commands entered on the rising clock edge (CLK)
- Programmable burst length = 2,4 or 8
- Bi-directional data strobe (DQS)
- DQS edge-aligned with data for READ; center aligned with data for WRITE
- DLL to align DQ and DQS transitions with input clocks
- Multi-bank internal architecture supporting concurrent operation
- Data mask inputs per byte (DQMLx and DQMHx)
- Programmable output drive (IOH/IOL)
- Auto precharge, auto refresh and self refresh (industrial only)

Austin Semiconductor, Inc. (ASI) is a fully QML certified, ISO registered company that supports the high reliability requirements of industries including Military, Aerospace, Transportation and Medical¹. ASI offers I/C components and modules / MCM's to their customers through a broad line of HI-REL and COTS products composed of standard & specialty memory and digital & analog solutions that are available in a wide array of ceramic and plastic packages. ASI also offers DMS services, obsolescence support and radiation tolerant products. ASI designs, develops and manufactures these products exclusively for the global HI-REL marketplace and service industry.

For additional information, contact:
David Harrison, VP of Market Development
DHarrison@austinsemiconductor.com
603.472.7477

¹ Diagnostic/Monitoring, Non-Life support Medical Applications

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